Chapter 4

Memory

Process Control

Flaxer Eli - Process Control

Ch 4 - 1

Outline

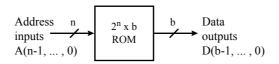
- **→** Read-Only Memory (ROM)
 - Internal Structure
 - Control and Timing
 - Static RAM (SRAM)
 - Internal Structure
 - Control and Timing
 - Dynamic RAM (DRAM)
 - Internal Structure
 - Control and Timing



Flaxer Eli - Process Control

Read-Only Memory (ROM)

• A combinational circuit with n inputs and b outputs:



- Programmable values determined by user
- Nonvolatile contents retained without power

Flaxer Eli - Process Control

Ch 4 - 3

Bit Line

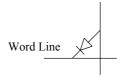
Types Of ROMs (1)

- Mask ROM
 - Connections made by the semiconductor vendor
 - Expensive setup cost
 - Several weeks for delivery
 - High volume only
 - Bipolar or MOS technology

PROM

- Programmable ROM
- Connections made by equipment manufacturer
- Vaporize (blow) fusible links with PROM programmer using high voltage/current pulses
- Bipolar technology
- One-time programmable

Flaxer Eli - Process Control



Types of ROMs (2)

EPROM

- Erasable Programmable ROM
- Charge trapped on extra "floating gate" of MOS transistors
- Exposure to UV light removes charge
 - 10-20 minutes
 - Quartz Lid = expensive package
- Limited number of erasures (10-100)

• EEPROM (E²ROM)

- Electrically Erasable ROM
- Floating gates charged/discharged electrically
- Not RAM! (relatively slow charge/discharge)
- limited number of charge/discharge cycles (10,000)



Bit Line

Word Line

Flaxer Eli - Process Control

Types of ROMs (3)

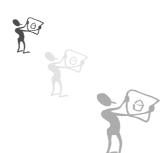
• Flash Memory

- Electronically erasable in blocks
- 100,000 erase cycles
- Simpler and denser than EEPROM

Flaxer Eli - Process Control

Outline

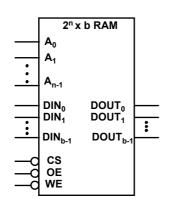
- Read-Only Memory (ROM)
 - Internal Structure
 - Control and Timing
- **→** Static RAM (SRAM)
 - Internal Structure
 - Control and Timing
 - Dynamic RAM (DRAM)
 - Internal Structure
 - Control and Timing

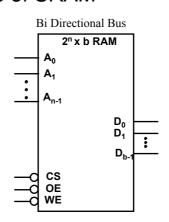


Flaxer Eli - Process Control

Ch 4 - 7

Basic Structure of SRAM

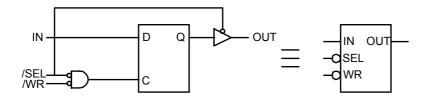




- Address/Control/Data Out lines like a ROM (Reading)
 - + Write Enable (WE) and Data In (DIN) (Writing)

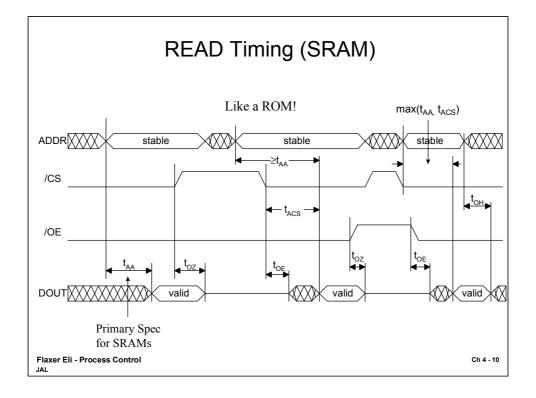
Flaxer Eli - Process Control

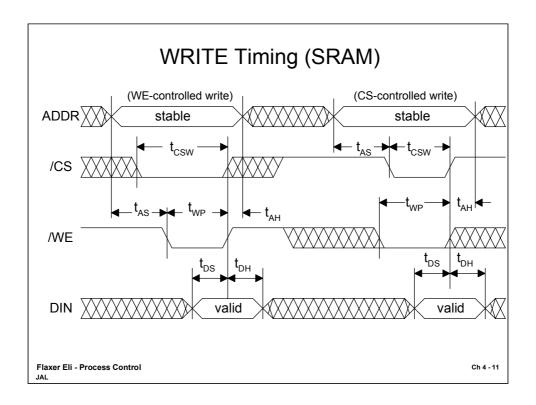
One Bit of SRAM



- SEL and WR asserted → IN data stored in D-latch (Write)
- SEL only asserted \rightarrow D-latch output enabled (Read)
- SEL not asserted \rightarrow No operation

Flaxer Eli - Process Control





RAM Summary

SRAM:

- Fast
- Simple Interface
- Moderate bit density (4 gates → 4 to 6 transistors)
- Moderate cost/bit

Small systems or very fast applications (cache memory)

DRAM (Dynamic RAM):

- moderate speed
- complex interface
- High bit density (1 transistor cell)
- Low cost/bit

Large Memories:
PC's
Mainframes

Flaxer Eli - Process Control